

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 4, at prenumbered line 22, has been amended as follows:

With reference to FIG. 4, the aluminum-extrusion heat sink fins (3) (3') and the aluminum-extrusion heat sinks (5) are connected through the penetrating holes (31) (31') (51) by the high-effect heat pipe (4). Accordingly, the heat of a chip of the circuit board (2) can be absorbed by the aluminum-extrusion heat sink fins (3) (3'), and also is conducted to the heat sinks (5) exposed to the power supply by the high-effect heat pipe (4) immediately, so that not only the heat is conducted out of the power supply, but also the aluminum-extrusion heat sinks take a cooling effect. Therefore, the power supply can reach an expected cooling effect without the cooling fan. ~~FIG. 5 shows a temperature distribution of cooling effect of the present invention.~~